



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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BGA Heat Sink - High Performance Straight Fin w/maxiGRIP



ATS Part#:	ATS-53375R-C1-R0
Description:	37.50 x 37.50 x 19.50 mm BGA Heat Sink - High Performance Straight Fin w/maxiGRIP
Heat Sink Type:	Straight Fin
Heat Sink Attachment:	maxiGRIP
Equivalent Part Number:	ATS-53375R-C2-R0 Discontinued

**Image above is for illustration purpose only.*

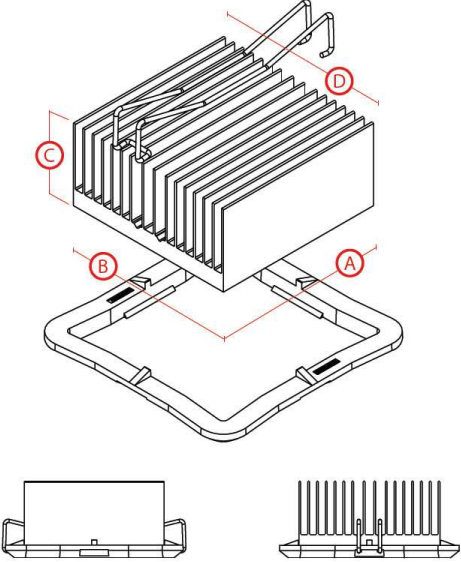
Features & Benefits

- High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- **maxiGRIP™** attachment applies steady, even pressure to the component and does not require holes in the PCB
- Designed specifically for BGAs and other surface mount packages
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock Testing and Unpackaged Drop Testing standards
- Comes preassembled with high performance, phase changing, thermal interface material

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.5 °C/W	2.7 °C/W	2.4 °C/W	2.1 °C/W	1.9 °C/W	1.8 °C/W	1.7 °C/W
	Ducted Flow	2.2	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
	37.50 mm	37.50 mm	19.50 mm	N/A mm	T766	BLACK-ANODIZED
<p>Notes:</p> <ul style="list-style-type: none">• Dimension A and B refer to component size.• Dimension C is the heat sink height from the bottom of the base to the top of the fin field.• ATS-53375R-C2-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint Gobain C1100F). NOTE: Saint Gobain C1100F is discontinued effective 12/31/10.• Thermal performance data are provided for reference only. Actual performance may vary by application.• ATS reserves the right to update or change its products without notice to improve the design or performance.• ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.• Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT170• Contact ATS to learn about custom options available.						

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